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U.S. Department of COMMERCE
United States Patent and Trademark Office

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HDP Docket No. 5731-000005/US
Express Mail Label No. EV 327051145 US

To the Director of the U.S. Patents ...d documents or the new address(es) below.

1.6.05

1. Name of conveying party(ies)/Execution Date(s):
Hing Poh Kuan

Execution Date(s) 1/3/05
Additional name of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies)
Name: Systems on Silicon Manufacturing Co. PTE. LTD.
Internal Address:
Street Address: 70, Pasir Ris Drive 1
City:
State:
Country: Singapore Zip: 519527
Additional Name(s) & address(es) attached? ☐ Yes ☒ No

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3. Nature of conveyance:
- ☒ Assignment
- ☐ Merger
- ☐ Security Agreement
- ☐ Change of Name
- ☐ Government Interest Assignment
- ☐ Executive Order 9424, Confirmatory License
- ☐ Other _____

4. Application number(s) or patent number(s): ☒ This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

01/10/2005 AKELECH1 00000031 11030500
04 FC:8021 40.00 OP

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning this document should be mailed:
Name: Matthew L. Cutler
Internal Address: Harness, Dickey & Pierce, P.L.C.
Street Address: 7700 Bonhomme, Suite 400
City: St. Louis
State: MO Zip: 63105
Phone Number : 314-726-7500
Fax Number: 314-726-7501
Email Address: mcutler@hdp.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) $ 40.00
- ☐ Authorized to be charged by credit card
- ☐ Authorized to be charged to deposit account
- ☒ Enclosed
- ☐ None required (government interest not affecting title)

8. Payment Information
a. Credit Card Last 4 Numbers _____
Expiration Date _____
b. Deposit Account Number 08-0750
Authorized User Name _____

9. Signature : Matthew Cutler
Signature
01/06/05
Date

Matthew L. Cutler
Name of Person Signing

Total number of pages including cover sheet, attachments, and documents 4

Documents to be recorded (including cover sheet) should be faxed to (703) 306-5995, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

ASSIGNMENT

Atty. Docket No.

WHEREAS, the undersigned, hereinafter referred to collectively as Assignor, has invented:

DELINEATION OF WAFERS

for which Assignor is about to make or has made United States or International application for patent

(a) ☒ executed on even date preparatory to filing (each inventor should sign this Assignment on the same day as he/she signs the Declaration and Power of Attorney);

(b) ☐ executed on _____, _____, _____; or

(c) ☐ filed on _____, and assigned Serial No. _____ or PCT International Application No. _____, and

WHEREAS, Systems On Silicon Manufacturing Co. PTE. Ltd., hereinafter referred to as Assignee, is desirous of acquiring an interest therein:

NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy whereof is hereby acknowledged, Assignor by these presents does sell, assign and transfer unto Assignee and its successors in interest, the full and exclusive right, title and interest in the United States of America and all foreign countries, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, to the said invention as described in the aforesaid application, said application for patent and all Letters Patent therefor to be held and enjoyed by Assignee to the full end of the term for which said Letters Patent are granted and any extensions thereof as fully and entirely as the same would have been held by Assignor had this assignment and sale not been made;

Assignor hereby covenants and agrees to execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent in the United States and in all foreign countries including, but not limited to, any provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, and as to letter patent any reissue, re-examination, or extension thereof, and for litigation regarding, or for the purpose of protecting title and to the said invention, the United States application for patent, or Letters Patent therefor, for the benefit of Assignee without further or other compensation than that above set forth;

Assignor hereby covenants that no assignment, sale or agreement or encumbrance has been or will be entered into which would conflict with this Assignment; and

Assignor hereby requests the Commissioner of Patents and Trademarks to issue said Letters Patent of the United States of America to Assignee, and requests that any official of any country or countries foreign to the United States, whose duty it is to issue or grant patents and applications as aforesaid, to issue said Letters Patent, Utility Model Registration or Inventor's Certificate to Assignee.

Assignor hereby authorizes and requests my attorney to insert here in parentheses (Application No. ________________, filed ________________) the filing date and application number of said application when known.

ASSIGNMENT

Full name of sole or first inventor: Kuan, Hing Poh

Inventor's signature: Kuan

Date: 3 - JAN - 2005

Residence: Block 75, #07-517, Commonwealth Drive, Singapore 140075

Citizenship: Malaysian

Mailing Address: Block 75, #07-517, Commonwealth Drive, Singapore 140075

WONG LIANG KEE
Witness

Witness

OATH

I/~~We~~, the undersigned, (A) KUAN, HING POH
(B) ____________________
(C) ____________________
(D) ____________________
(E) ____________________

hereby declare that I am/~~we are~~ the original and sole/~~joint~~ inventor(s) of the invention/~~utility mode/new design~~ entitled:

DELINEATION OF WAFERS

I/~~we~~ further declare that these statements were with the knowledge that willful false statements and the like so made are punishable under the laws of Taiwan, the Republic of China.

ASSIGNMENT

I/~~We~~ hereby also agree to assign the patent application right
(including priority right) in Taiwan, R.O.C. to
SYSTEMS ON SILICON MANUFACTURING CO. PTE. LTD. residing at
(the full name of assignee, if any)

70 PASIR RIS DRIVE 1,
SINGAPORE 519527

Signed by Inventor (A): ____________________
Address: BLOCK 75, #07-517, COMMONWEALTH DRIVE, SINGAPORE 140075
Signed by Inventor (B): ____________________
Address: ____________________
Signed by Inventor (C): ____________________
Address: ____________________
Signed by Inventor (D): ____________________
Address: ____________________
Signed by Inventor (E): ____________________
Address: ____________________

Dated this 3rd day of JAN 2005

Oath & Assignment
For Patent Applications in Taiwan, RO.C. **(No Legalization required)**